

# 74ABT841

10-bit bus interface latch; 3-state

Rev. 4 — 7 November 2011

Product data sheet

## 1. General description

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The 74ABT841 high performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT841 bus interface register is designed to provide extra data width for wider data/address paths of buses carrying parity.

The 74ABT841 consists of ten D-type latches with 3-state outputs. The flip-flops appear transparent to the data when latch enable (LE) is HIGH. This allows asynchronous operation, as the output transition follows the data in transition. On the LE HIGH-to-LOW transition, the data that meets the set-up and hold time is latched.

Data appears on the bus when the output enable ( $\overline{OE}$ ) is LOW. When  $\overline{OE}$  is HIGH the output is in the high-impedance state.

## 2. Features and benefits

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- High speed parallel latches
- Extra data width for wide address/data paths or buses carrying parity
- Ideal where high speed, light loading, or increased fan-in are required with MOS microprocessors
- Broadside pinout
- Output capability: +64 mA and –32 mA
- Power-up 3-state
- Power-up reset
- Latch-up protection exceeds 500 mA per JESD78B class II level A
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V

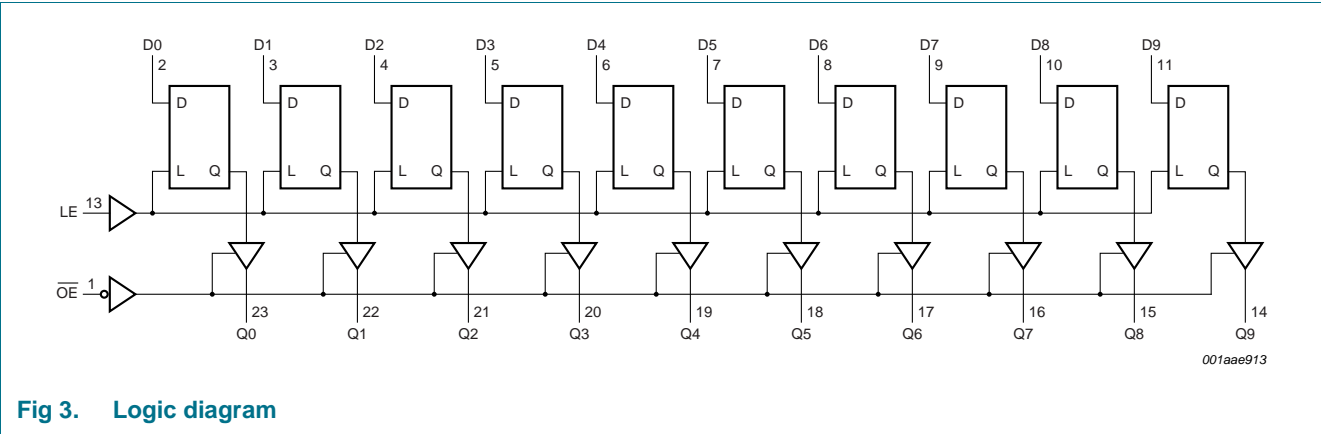
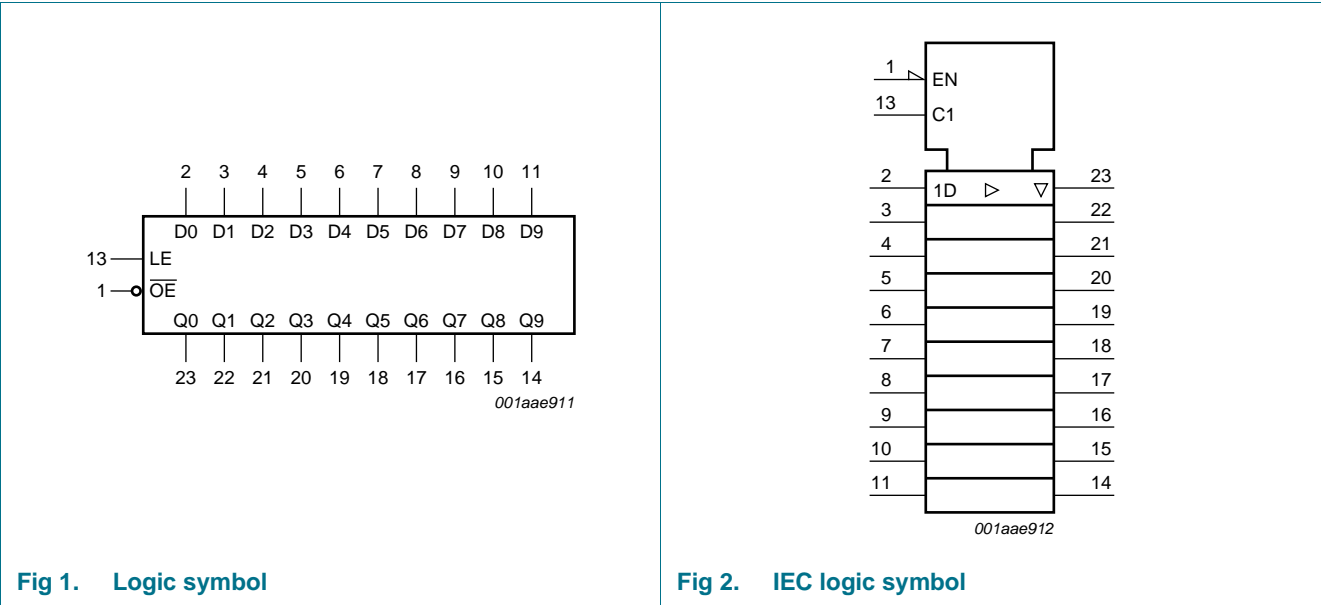


3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74ABT841D	−40 °C to +85 °C	SO24	plastic small outline package; 24 leads; body width 7.5 mm	SOT137-1
74ABT841DB	−40 °C to +85 °C	SSOP24	plastic shrink small outline package; 24 leads; body width 5.3 mm	SOT340-1
74ABT841PW	−40 °C to +85 °C	TSSOP24	plastic thin shrink small outline package; 24 leads; body width 4.4 mm	SOT355-1

4. Functional diagram



5. Pinning information

5.1 Pinning

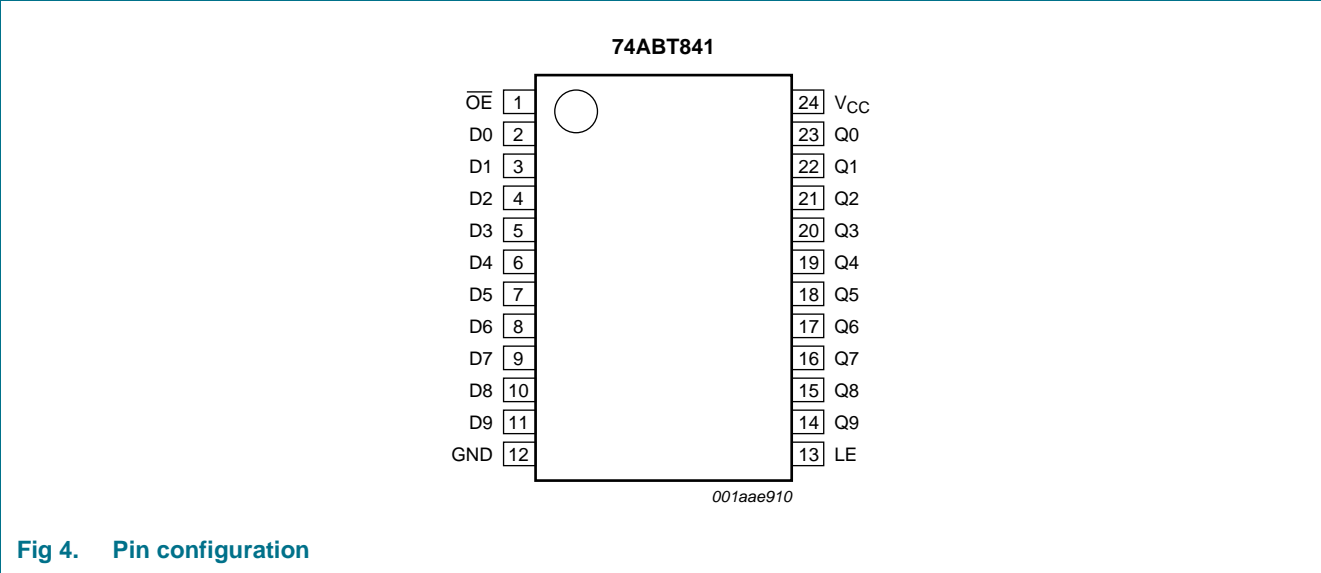


Fig 4. Pin configuration

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{OE}$	1	output enable input (active LOW)
D0 to D9	2, 3, 4, 5, 6, 7, 8, 9,10, 11	data input
GND	12	ground (0 V)
LE	13	latch enable input (active falling edge)
Q0 to Q9	23, 22, 21, 20, 19, 18, 17, 16, 15, 14	data output
$V_{CC}$	24	positive supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Input			Output Q0 to Q9	Operating mode
OE	LE	nD		
L	H	L	L	transparent
L	H	H	H	
L	↓	L	L	latched
L	↓	h	H	
H	X	X	Z	high-impedance
L	L	X	NC	hold

- [1] H = HIGH voltage level;  
 h = HIGH voltage level one set-up time prior to the LOW-to-HIGH LE transition;  
 L = LOW voltage level;  
 l = LOW voltage level one set-up time prior to the LOW-to-HIGH LE transition;  
 ↓ = HIGH-to-LOW clock transition;  
 NC = no change;  
 X = don't care;  
 Z = high-impedance OFF-state.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7.0	V
V <sub>I</sub>	input voltage		<sup>[1]</sup> -1.2	+7.0	V
V <sub>O</sub>	output voltage	output in OFF-state or HIGH-state	<sup>[1]</sup> -0.5	+5.5	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V	-18	-	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < 0 V	-50	-	mA
I <sub>O</sub>	output current	output in LOW-state	-	128	mA
T <sub>j</sub>	junction temperature		<sup>[2]</sup> -	150	°C
T <sub>stg</sub>	storage temperature		-65	+150	°C

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 [2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		4.5	-	5.5	V
$V_I$	input voltage		0	-	$V_{CC}$	V
$V_{IH}$	HIGH-level input voltage		2.0	-	-	V
$V_{IL}$	LOW-level input voltage		-	-	0.8	V
$I_{OH}$	HIGH-level output current		-32	-	-	mA
$I_{OL}$	LOW-level output current		-	-	64	mA
$\Delta t/\Delta V$	input transition rise and fall rate		0	-	5	ns/V
$T_{amb}$	ambient temperature	in free air	-40	-	+85	°C

## 9. Static characteristics

**Table 6. Static characteristics**

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		Unit	
			Min	Typ	Max	Min	Max		
V <sub>IK</sub>	input clamping voltage	V <sub>CC</sub> = 4.5 V; I <sub>IK</sub> = −18 mA	−1.2	−0.9	-	−1.2	-	V	
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>							
		V <sub>CC</sub> = 4.5 V; I <sub>OH</sub> = −3 mA	2.5	3.5	-	2.5	-	V	
		V <sub>CC</sub> = 5.0 V; I <sub>OH</sub> = −3 mA	3.0	4.0	-	3.0	-	V	
		V <sub>CC</sub> = 4.5 V; I <sub>OH</sub> = −32 mA	2.0	2.6	-	2.0	-	V	
V <sub>OL</sub>	LOW-level output voltage	V <sub>CC</sub> = 4.5 V; I <sub>OL</sub> = 64 mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	-	0.42	0.55	-	0.55	V	
V <sub>OL(pu)</sub>	power-up LOW-level output voltage	V <sub>CC</sub> = 5.5 V; I <sub>O</sub> = 1 mA; V <sub>I</sub> = GND or V <sub>CC</sub>	[1]	-	0.13	0.55	-	0.55	V
I <sub>I</sub>	input leakage current	V <sub>CC</sub> = 5.5 V; V <sub>I</sub> = GND or 5.5 V							
		control pins	-	±0.01	±1.0	-	±1.0	μA	
		data pins	-	±5	±100	-	±100	μA	
I <sub>OFF</sub>	power-off leakage current	V <sub>CC</sub> = 0 V; V <sub>I</sub> or V <sub>O</sub> ≤ 4.5 V	-	±5.0	±100	-	±100	μA	
I <sub>O(pu/pd)</sub>	power-up/power-down output current	V <sub>CC</sub> = 2.0 V; V <sub>O</sub> = 0.5 V; V <sub>I</sub> = GND or V <sub>CC</sub> ; $\overline{\text{OE}}$ n HIGH	[2]	-	±5.0	±50	-	±50	μA
I <sub>OZ</sub>	OFF-state output current	V <sub>CC</sub> = 5.5 V; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>							
		V <sub>O</sub> = 2.7 V	-	5.0	50	-	50	μA	
		V <sub>O</sub> = 0.5 V	-	−5.0	−50	-	−50	μA	
I <sub>LO</sub>	output leakage current	HIGH-state; V <sub>O</sub> = 5.5 V; V <sub>CC</sub> = 5.5 V; V <sub>I</sub> = GND or V <sub>CC</sub>	-	5.0	50	-	50	μA	
I <sub>O</sub>	output current	V <sub>CC</sub> = 5.5 V; V <sub>O</sub> = 2.5 V	[3]	−180	−100	−50	−180	−50	mA

Table 6. Static characteristics ...continued

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		Unit
			Min	Typ	Max	Min	Max	
I <sub>CC</sub>	supply current	V <sub>CC</sub> = 5.5 V; V <sub>I</sub> = GND or V <sub>CC</sub>						
		outputs HIGH-state	-	0.5	250	-	250	μA
		outputs LOW-state	-	25	38	-	38	mA
		outputs disabled	-	0.5	250	-	250	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>CC</sub> = 5.5 V; one input at 3.4 V; other inputs at V <sub>CC</sub> or GND [4]	-	0.5	1.5	-	1.5	mA
C <sub>I</sub>	input capacitance	V <sub>I</sub> = 0 V or V <sub>CC</sub>	-	4	-	-	-	pF
C <sub>O</sub>	output capacitance	outputs disabled; V <sub>O</sub> = 0 V or V <sub>CC</sub>	-	7	-	-	-	pF

[1] For valid test results, data must not be loaded into the flip-flops (or latches) after applying the power.

[2] This parameter is valid for any V<sub>CC</sub> between 0 V and 2.1 V with a transition time of up to 10 ms. For V<sub>CC</sub> = 2.1 V to V<sub>CC</sub> = 5 V ± 10 %, a transition time of up to 100 μs is permitted.

[3] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[4] This is the increase in supply current for each input at 3.4 V.

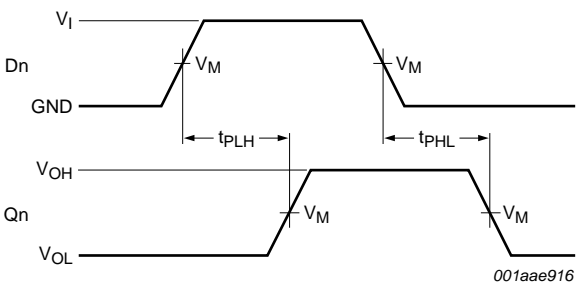
## 10. Dynamic characteristics

Table 7. Dynamic characteristics

GND = 0 V; for test circuit, see [Figure 9](#).

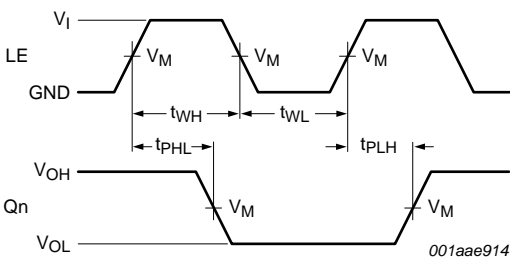
Symbol	Parameter	Conditions	25 °C; V <sub>CC</sub> = 5.0 V			–40 °C to +70 °C; V <sub>CC</sub> = 5.0 V ± 0.5 V		Unit
			Min	Typ	Max	Min	Max	
t <sub>PLH</sub>	LOW to HIGH propagation delay	Dn to Qn; see <a href="#">Figure 5</a>	2.1	4.1	5.5	2.1	6.2	ns
		LE to Qn; see <a href="#">Figure 6</a>	2.1	4.1	5.9	2.1	6.5	ns
t <sub>PHL</sub>	HIGH to LOW propagation delay	Dn to Qn; see <a href="#">Figure 5</a>	2.0	4.0	5.5	2.0	6.2	ns
		LE to Qn; see <a href="#">Figure 6</a>	2.8	4.6	6.2	2.8	6.7	ns
t <sub>PZH</sub>	OFF-state to HIGH propagation delay	$\overline{OE}$ to Qn; see <a href="#">Figure 7</a>	1.0	3.0	4.5	1.0	5.3	ns
t <sub>PZL</sub>	OFF-state to LOW propagation delay	$\overline{OE}$ to Qn; see <a href="#">Figure 7</a>	2.2	4.1	5.6	2.2	6.3	ns
t <sub>PHZ</sub>	HIGH to OFF-state propagation delay	$\overline{OE}$ to Qn; see <a href="#">Figure 7</a>	2.7	4.7	6.2	2.7	7.1	ns
t <sub>PLZ</sub>	LOW to OFF-state propagation delay	$\overline{OE}$ to Qn; see <a href="#">Figure 7</a>	2.8	4.6	6.1	2.8	6.5	ns
t <sub>su(H)</sub>	set-up time HIGH	Dn to LE; see <a href="#">Figure 8</a>	2.5	1.0	-	2.5	-	ns
t <sub>su(L)</sub>	set-up time LOW	Dn to LE; see <a href="#">Figure 8</a>	1.5	0	-	1.5	-	ns
t <sub>h(H)</sub>	hold time HIGH	Dn to LE; see <a href="#">Figure 8</a>	1.5	0.2	-	1.5	-	ns
t <sub>h(L)</sub>	hold time LOW	Dn to LE; see <a href="#">Figure 8</a>	+1.0	–0.8	-	1.0	-	ns
t <sub>WH</sub>	pulse width HIGH	LE; see <a href="#">Figure 6</a>	3.3	1.9	-	3.3	-	ns
t <sub>WL</sub>	pulse width LOW	LE; see <a href="#">Figure 6</a>	3.3	1.9	-	3.3	-	ns

11. Waveforms



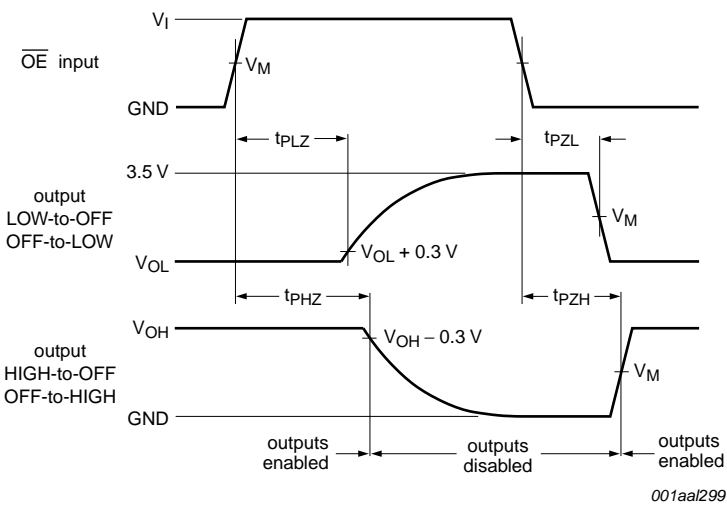
$V_M = 1.5\text{ V}$   
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

Fig 5. Propagation delay for data to output



$V_M = 1.5\text{ V}$   
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

Fig 6. Propagation delay, latch enable input to output and enable pulse width



$V_M = 1.5\text{ V}$   
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

Fig 7. 3-state output (Qn) enable and disable times

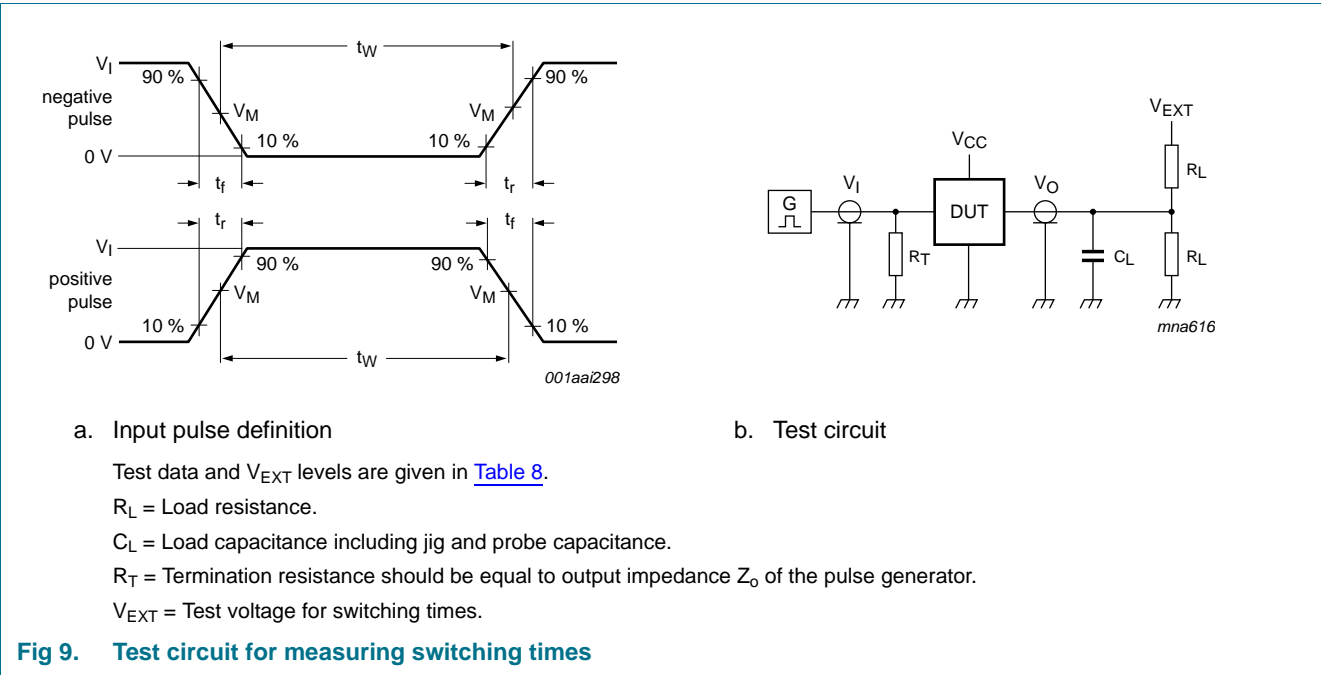
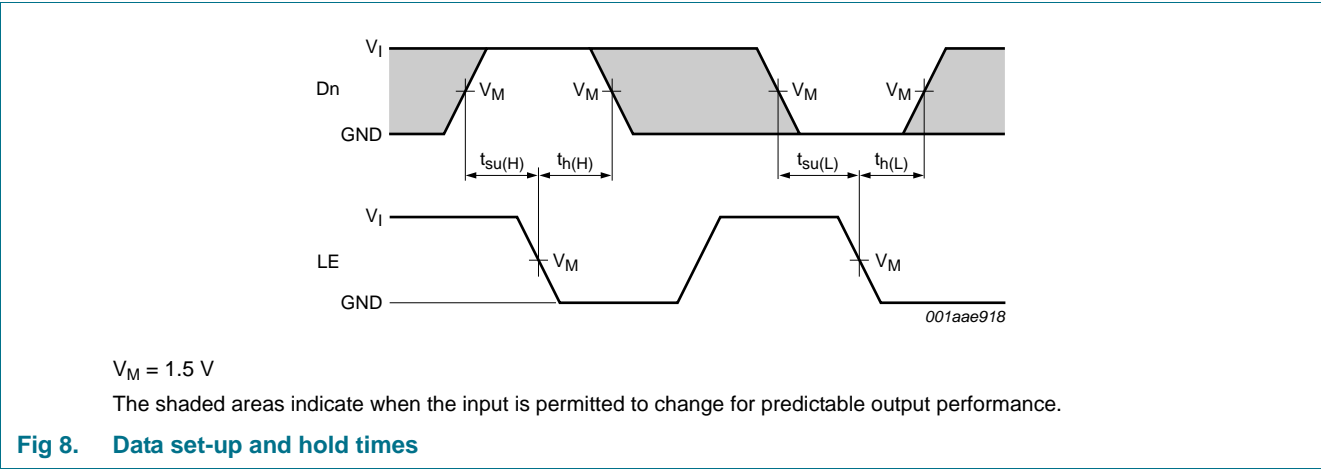


Table 8. Test data

Input				Load		$V_{EXT}$		
$V_I$	$f_I$	$t_W$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
3.0 V	1 MHz	500 ns	$\leq 2.5\text{ ns}$	50 pF	500 $\Omega$	open	open	7.0 V



12. Package outline

SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1

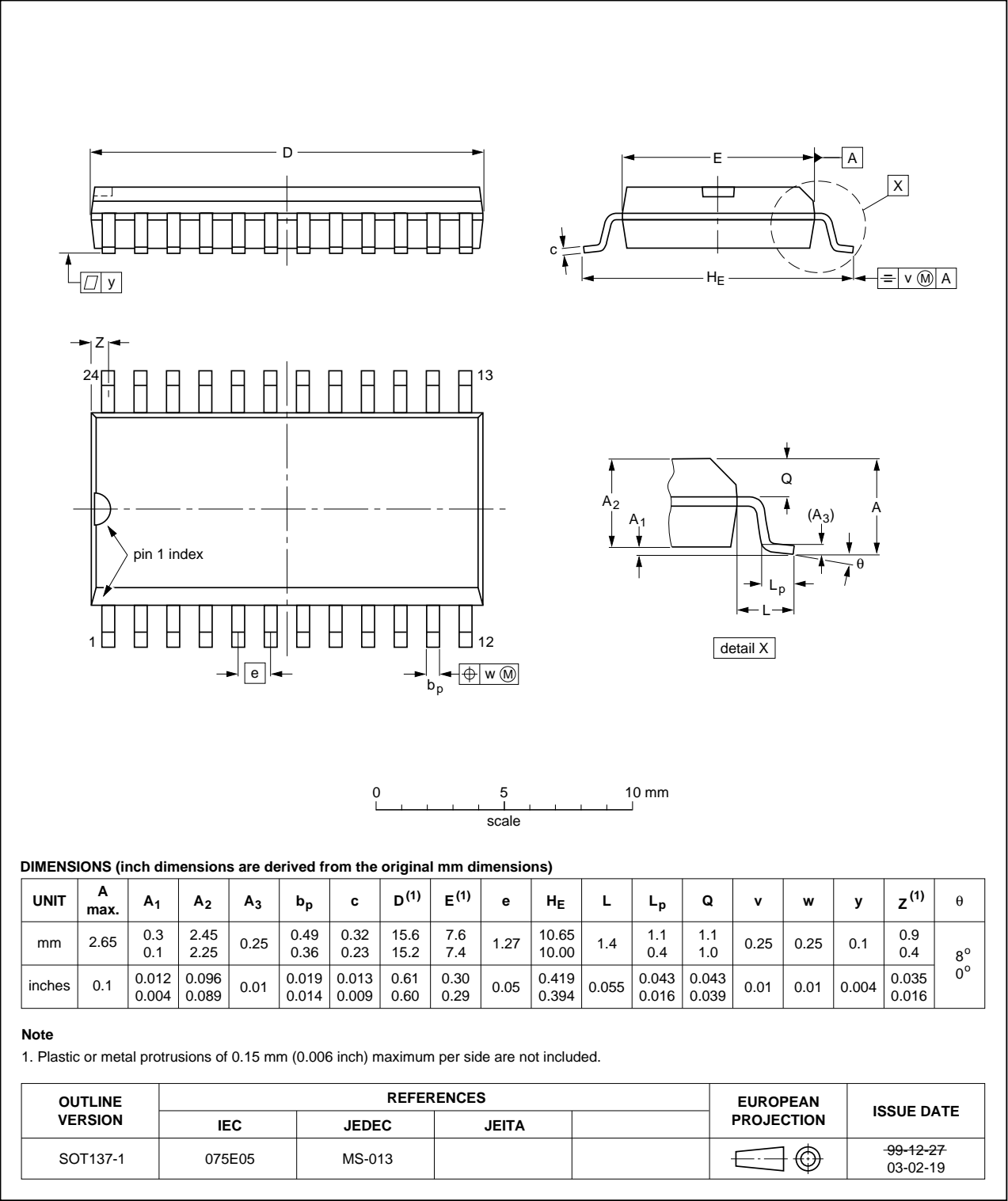


Fig 10. Package outline SOT137-1 (SO24)

SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1

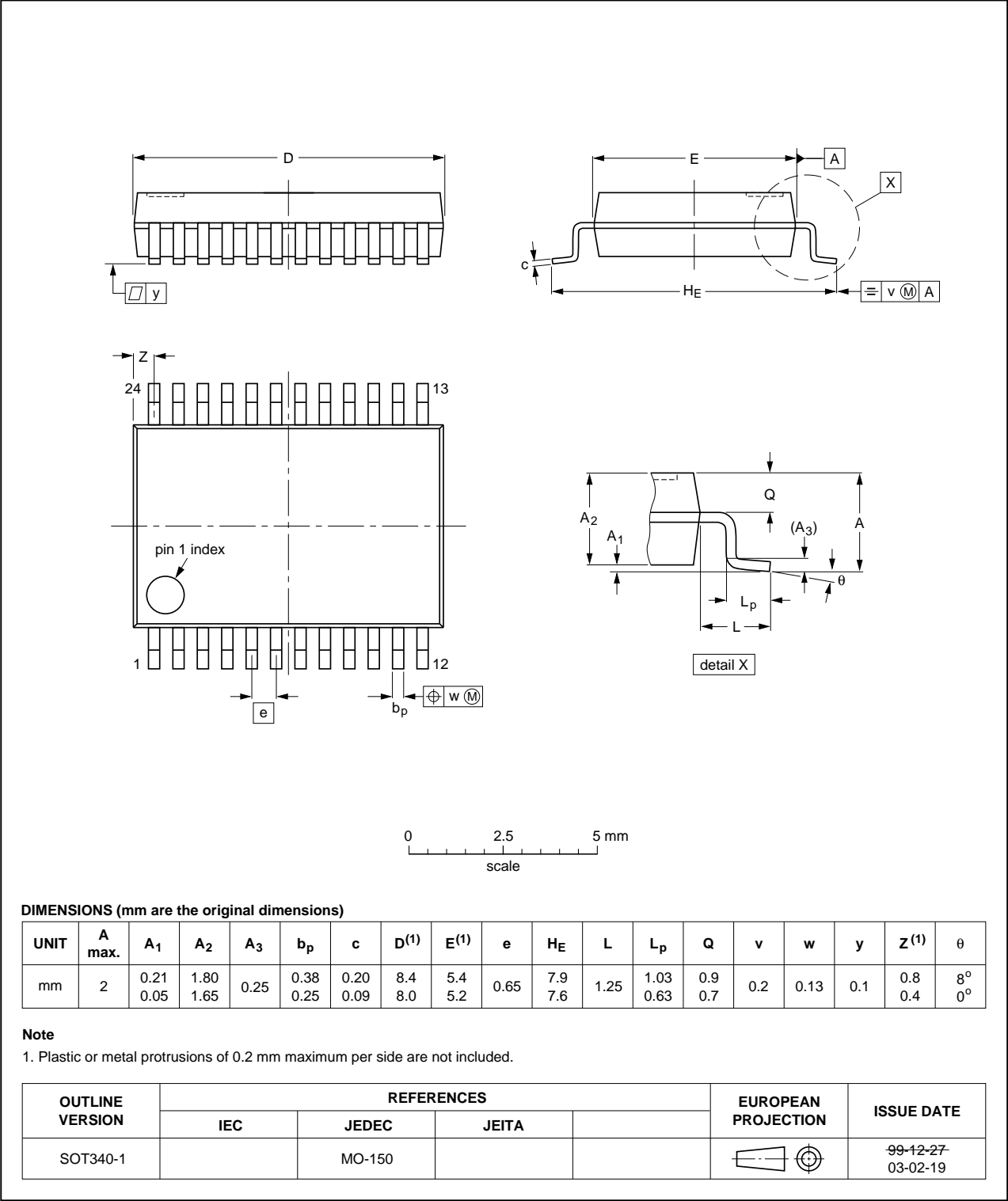
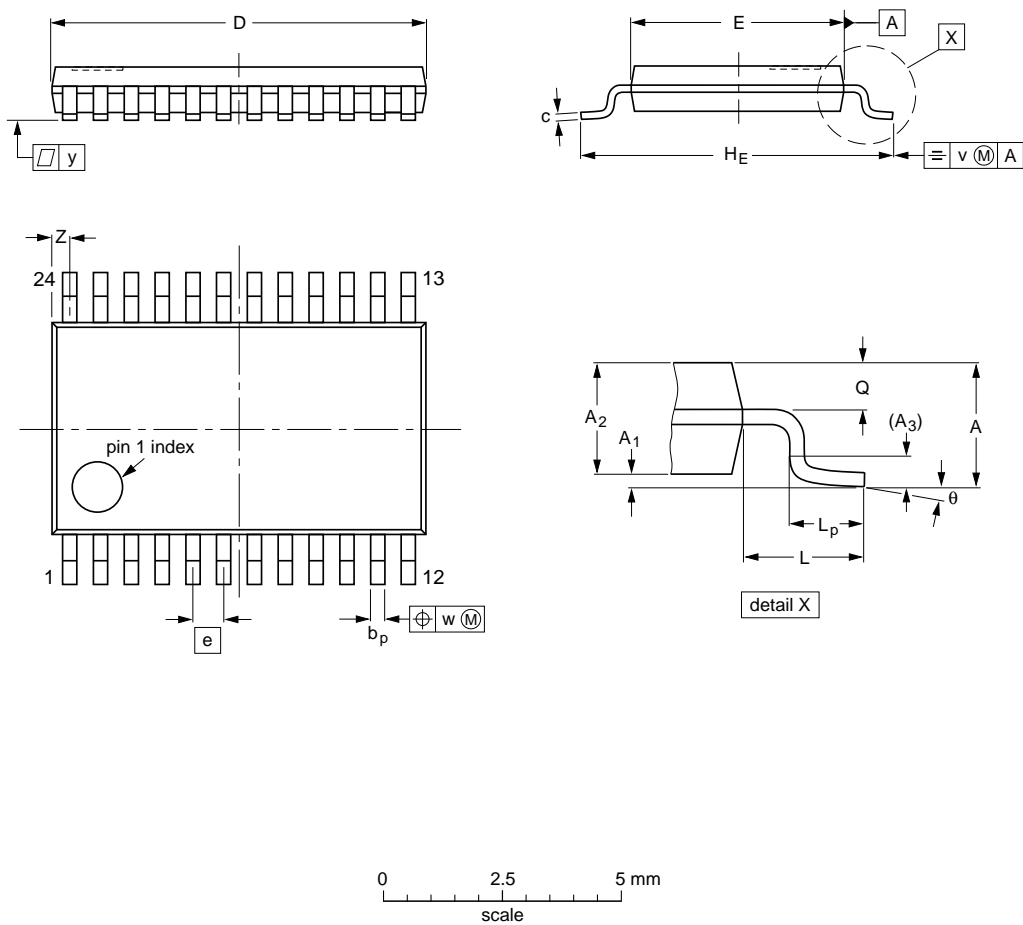


Fig 11. Package outline SOT340-1 (SSOP24)

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT355-1		MO-153				99-12-27 03-02-19

Fig 12. Package outline SOT355-1 (TSSOP24)

## 13. Abbreviations

Table 9. Abbreviations

Acronym	Description
BiCMOS	Bipolar Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ABT841 v.4	20111107	Product data sheet	-	74ABT841 v.3
Modifications:	• Legal pages updated.			
74ABT841 v.3	20100325	Product data sheet	-	74ABT841 v.2
74ABT841 v.2	20100302	Product data sheet	-	74ABT841
74ABT841	19950906	Product specification	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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